

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)	Application Number		09928737	
	Filing Date		2001-08-13	
	First Named Inventor	QUAN, SON KY		
	Art Unit	2831		
	Examiner Name	NGO, HUNG V.		
Attorney Docket Number		SC09785T-CD1		

U.S. PATENTS						Remove
Examiner Initial*	Cite No	Patent Number	Kind Code ¹	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
	1	5341039		1994-08-23	FUKUMOTO	

If you wish to add additional U.S. Patent citation information please click the Add button.

Add

U.S. PATENT APPLICATION PUBLICATIONS						Remove
Examiner Initial*	Cite No	Publication Number	Kind Code ¹	Publication Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
	1					

If you wish to add additional U.S. Published Application citation information please click the Add button.

Add

FOREIGN PATENT DOCUMENTS								Remove
Examiner Initial*	Cite No	Foreign Document Number ³	Country Code ² j	Kind Code ⁴	Publication Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear	T ⁵
	1							<input type="checkbox"/>

If you wish to add additional Foreign Patent Document citation information please click the Add button.

Add

NON-PATENT LITERATURE DOCUMENTS			Remove
Examiner Initials*	Cite No	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ⁵

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Not for submission under 37 CFR 1.99)

Application Number	09928737
Filing Date	2001-08-13
First Named Inventor	QUAN, SON KY
Art Unit	2831
Examiner Name	NGO, HUNG V.
Attorney Docket Number	SC09785T-CD1

1	NGUYEN, L. T., et al., "Leadframe Designs for Minimum Molding-Induced Warpage," Electronic Components and Technology Conference, 1994, Proceedings., 44th, pgs. 513-520	<input type="checkbox"/>
2	JEDEC MO-151, S-PXGA-XIPBGA Plastic Ball Grid Array Family Registration, November 1993	<input type="checkbox"/>
3	ITC, Redacted Order No. 34 - ID Granting Respondent MSD of Non-Infringement of the '306 CBI, January 6, 2011	<input type="checkbox"/>
4	ITC, FSI Petition re Order 34 on Non-Infringement of the '306 Patent, January 14, 2011	<input type="checkbox"/>

If you wish to add additional non-patent literature document citation information please click the Add button

EXAMINER SIGNATURE

Examiner Signature	Date Considered
--------------------	-----------------

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through a citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ See Kind Codes of USPTO Patent Documents at www.USPTO.GOV or MPEP 901.04. ² Enter office that issued the document, by the two-letter code (WIPO Standard ST.3). ³ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁴ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁵ Applicant is to place a check mark here if English language translation is attached.